TECHNICAL DATA SHEET

PF606-P25 No Clean Solder Paste

Specification:

No	Item	Specification	Standard
1	Appearance	Gray Paste, No Foreign, No Stiff	
2	Alloy	Sn/Ag3/Cu0.5	JIS-Z-3282
3	Melting Point	217°C~219°C	DSC
4	Particle Size	(Type 3) +45µm 1% less, –20µm 10% less (Type 4) +38µm 1% less, –20µm 10% less	IPC-TM-650, 2.2.14
5	Powder Shape	Sphere	
6	Flux Content	11.5 ± 1.0 wt%	JIS-Z-3197, 6.1
7	Halide Content	<0.09 wt% (in flux)	BS EN14582
8	Viscosity	200 ± 30 Pa.S (25±1°C, 10rpm, Malcom)	JIS-Z-3284, Annex 6
9	Flux Type	ROL0	J-STD-004
10	RoHS Compliant	Yes	International Standards

Physical Properties & Reliability Data

No	Test Item	Test Result	Test Method
1	Copper Plate Corrosion Test	PASS	JIS-Z-3197, 6.6.1
2	Spread Test	70% up	JIS-Z-3197, 6.10
3	Silver Chromate Test	PASS	IPC-TM-650, 2.3.33
4	Copper Mirror Test	PASS	IPC-TM-650, 2.3.32
5	Fluorides By Spot Test	PASS	IPC-TM-650, 2.3.35.1
6	S.I.R Test ▲	$1\times10^{9}\Omega$up	IPC-TM-650, 2.6.3.3
7	Electro Migration Test ◆	$1\times10^{12}\Omega$up Pass	IPC-TM-650, 2.6.14.1
8	Viscosity Test (25°C,10rmp)	200 ± 30 Pa.s	JIS-Z-3284. Annex 6
9	Tack Test (gf)	130 up (8hr)	JIS-Z-3284. Annex 9
10	Slump Test	Less than 0.3 mm	JIS-Z-3284. Annex 8
11	Solder Ball Test	PASS	JIS-Z-3284. Annex 11

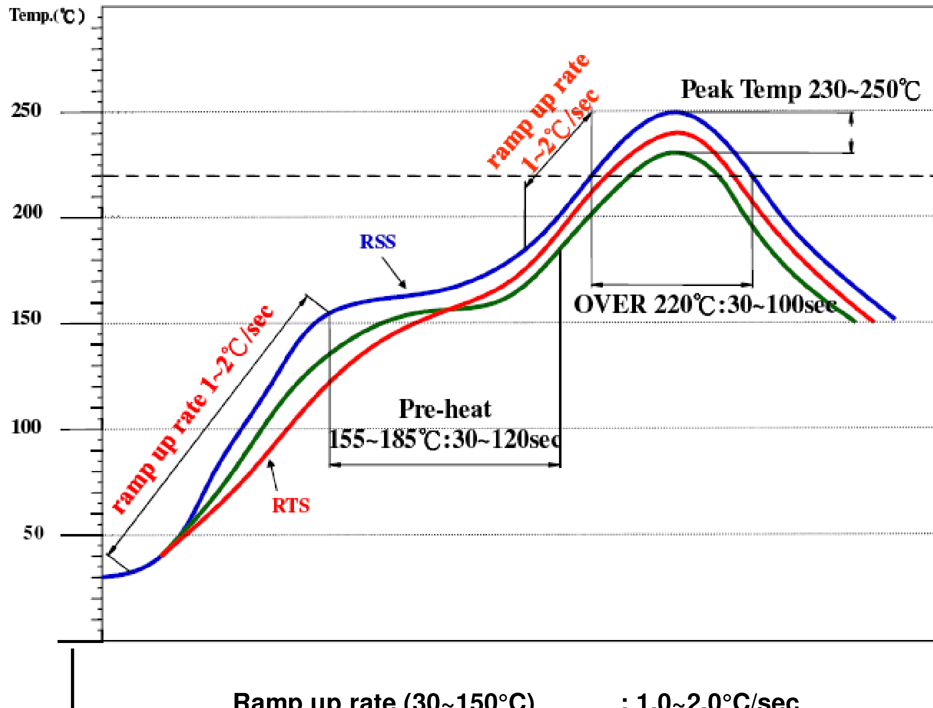
▲Test Conditions : 85°C, 85% RH ◆Test Conditions: 65°C, 85% RH

ALLOY COMPOSITION in %

(Sn)	(Ag)	(Cu)	(Ni)	(Ge)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)	(Pb)
REM.	2.8~ 3.2	0.3~ 0.7	0.0~ 0.01	0.0~ 0.01	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.10 MAX	0.002 MAX	0.05 MAX

Japanese Patent No: 3296289 US Patent No.: 6179935B1.

Temperature Profile



Ramp up rate (30~150°C)	: 1.0~2.0°C/sec
Preheat time (155~185°C)	: 30~120 sec
Time above 220°C	: 30~100 sec
Ramp up rate during Reflow	: 1.0~2.0°C/sec
Peak temperature	: 230~250°C
Ramp down rate during cooling	: 1.0~6.0°C/sec

Handling and Storage Instruction

1. Storage

(1) Keep in 0~10°C temperature.

(2) Expiration period: 6 months from production date. 7 days storage in (25 ± 2°C) (sealed condition)

(3) Keep out of direct sunlight.

2. Operation Manual (Sealed)

(1) Keep solder paste in room temperature (25 ± 2°C) for 3~4 hours. Do not use any heater to raise temperature.

(2) Kindly mixed averagely for 1~3 minutes according to necessity.

3. Operation Manual (Opened)

(1) At first, add 2/3 can of solder paste onto the stencil, do not add more than 1 can of each.

(2) Add solder paste a little at a time according to production procedure.

(3) To maintain the solder paste quality, please make sure not to store the opened can with sealed can.

(4) Use new opened solder paste at the beginning of the next day. Mix opened solder paste with sealed one at ratio 1:2, add little at a time during printing.

(5) Soon after printing, please make sure all components to be mount on printed circuit board between 4~6 hours.

(6) Please withdraw solder paste from stencil and seal it in paste container, if printing process would pause for more than 1 hour.

(7) After continuously printing for 24 hours, kindly withdraw printed solder paste and follow step (4).

(8) It is recommended to clean both side of stencil every 4 hours manually to ensure printing quality.

(9) Kindly keep room temperature between 22~28°C, room humidity RH 30~60% is recommended.

(10) To clean up the defect printed board, kindly use isopropyl alcohol or IPA.

For more details, please visit Our Website at www.persangalloy.com or write to us.

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